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PATENTS ONLY

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U.S. DEPARTMENT OF COMMERCE
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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof

1. Name of conveying party(ies):

Hisayuki Takasu, Kouichi Miyazawa, and Toru Iwaya

11-13-03

Additional name(s) of conveying party(ies) attached?

☐ Yes☒ No

3. Nature of Conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

Execution Date: November 5, 2003

2. Name and address of receiving party(ies)

Name: Hitachi Science Systems, Ltd.

Internal Address:

Street Address:

1040, Ichige
Hitachinaka-shi
Ibaraki 312-0033
Japan

City:

Country:

Zip:

Additional name(s) &
address(es) attached:☐ Yes☒ No

4. Application number(s) or patent number(s):

10705845

If this document is being filed together with a new application, the execution date of the new application is: November 5, 2003

A. Patent Application No.(s):

This application

B. Patent No.(s):

Additional numbers attached?

☐ Yes☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Mark J. Thronson

DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP

Internal Address: Atty. Dkt.: N9460.0018/P018

Street Address:
2101 L Street NW

City:

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State:

DC

Zip:

20037-1526

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41)

\$ 40.00

☐ Enclosed☒ Authorized to be charged to deposit account☒ Authorized to be charged to credit card
(Form 2038 enclosed)

8. Deposit account number:

04-1073

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Mark J. Thronson (33,082)

Name of Person Signing

Signature

November 13, 2003

Date

Total number of pages including cover sheet, attachments, and documents: 2

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40.00 DP

ASSIGNMENT

(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi Science Systems, Ltd., a corporation organized under the laws of Japan, located at 1040, Ichige, Hitachinaka-shi, Ibaraki 312-0033, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi Science Systems, Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

A METHOD OF DEVELOPING A RESIST FILM AND A RESIST DEVELOPMENT PROCESSOR

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi Science Systems, Ltd., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Science Systems, Ltd.

Signed on the date(s) indicated aside signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Hisayuki Takasu</u>	<u>11/5/2003</u>
2) <u>Koichi Higazawa</u>	<u>11/5/2003</u>
3) <u>Toru Inaya</u>	<u>11/5/2003</u>
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____